Internship: Dry/Plasma Etch Research and Development

As an Intern in the Dry (plasma) Etch Research and Development Group in Boise, ID, you will design and optimize plasma etch processes for Micron's leading edge memory products.   Primary areas of responsibility include plasma dry etch process characterization, optimization, design, troubleshooting, process transfer and fundamental research. Dry Etch Process Development Interns interact with groups such as process integration, electrical failure analysis, yield enhancement, manufacturing, and equipment vendors to ensure robust etch processes that meet the precise physical and electrical requirements for Micron products. The particular project envisioned for summer 2014 interns is reactor scale plasma modeling in support of hardware and process optimization for 3D NAND. Hence, applicants with a modeling and simulation background are preferred. However, all applicants in the midst of graduate level education with a research focus in plasma science and engineering will be considered.

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